| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|----------|-------|--|---|---------------------|---------|------------------|
| S1 | | "6497801".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/06 10:19 |
| S2 | 2 | "6261433".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/06 10:22 |
| S3 | 20 | (Landau near2 Uziel).in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR · | ON | 2005/07/06 10:22 |
| S4 | | ("3649509" "3727620" "3770598" "4027686" "4092176" "4110176" "4113492" "4315059" "4326940" "4336114" "4376685" "4405416" "4428815" "4435266" "4489740" "4510176" "4518678" "4519846" "4693805" "4732785" "4789445" "5039381" "5055425" "5092975" "5155336" "5162260" "5222310" "5224504" "5230743" "5252807" "5256274" "5259407" "5290361" "5316974" "5328589" "5349978" "53429733" "5447615" "5516412" "5608943" "5705223" "5718813" "5723028").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 08:58 |
| S5 | 1 | "6391166".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 09:34 |
| S6 | 86456 | (segment\$3 or plurality) near3 (anode or electrode or cathode) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 09:55 |

| S7 | 17997 | (anode or cathode or electrode) | US-PGPUB; | OR | ON | 2005/07/10 10:29 |
|-----------|--------|--|----------------------------------|----|----|------------------|
| | _,,,,, | with (independent or different or own or individual) near3 (power or voltage or current) | USPAT; USOCR | | 5 | -300,0.,10 10.25 |
| S13 | 6941 | S6 and S7 | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 09:55 |
| S14 | 2245 | S13 and (semiconductor or wafer) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 09:55 |
| S15 | 406 | S14 and (anode or cathode or electrode) near5 (ring or concentric or coaxial or annular) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 10:26 |
| S17 | 318 | S15 and (plating or polishing or etching or deposit\$4) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 10:31 |
| S18 | 92 | S17 and ("204"/\$.ccls. or "205"/\$.ccls.) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 10:23 |
| S20 | 20461 | (segment\$3 or plurality) near3 (anode or electrode or cathode) | EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/10 10:23 |
| S21 | 3937 | (anode or cathode or electrode) with (independent or different or own or individual) near3 (power or voltage or current) | EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/10 10:23 |
| S22 | 3316 | S20 and (semiconductor or wafer) | EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/10 10:26 |
| S23 | 0 | S22 and (plating or polishing or etching or deposit\$4) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 10:26 |
| S25 | 0 | S22 and (electroplating or (electro adj plating)) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 10:25 |
| S27 | 50 | S22 and (anode or cathode or electrode) near5 (ring or concentric or coaxial or annular) | EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/10 10:27 |
| S28 | 27929 | S6 and (semiconductor or wafer) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 10:29 |
| S29 | 2538 | S28 and (anode or cathode or electrode) near5 (ring or concentric or coaxial or annular) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 10:29 |
| S30 | 406 | S29 and (anode or cathode or electrode) with (independent or different or own or individual) near3 (power or voltage or current) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 10:30 |

| S31 | 318 | S30 and (plating or polishing or etching or deposit\$4) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 10:31 |
|-----|------|--|------------------------------|------|------|------------------|
| S32 | 109 | (204/230.7).ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 10:32 |
| S33 | 15 | S32 and (semiconductor or wafer) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 10:35 |
| S34 | 1167 | "204"/\$.ccls. and (semiconductor or wafer) and (auxiliary or second\$4) adj (electrode or anode or cathode) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 11:24 |
| S35 | 281 | S34 and plating | US-PGPUB; USPAT; USOCR | OR | ON . | 2005/07/10 12:07 |
| S37 | 190 | S34 and (electroplating or (electro adj plating) or (electrochemical adj plating) or (electrochemical adj processing)) | US-PGPUB; USPAT; USOCR | OR . | ON | 2005/07/10 12:09 |
| S38 | 54 | S37 and auxiliary | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 12:14 |
| S39 | 1 | "3755113".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 12:14 |
| S40 | 3225 | electroplating and ((revers\$4 or chang\$4 or var\$3) near3 current) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 12:15 |
| S41 | 677 | electroplating and ((revers\$4 or chang\$4 or var\$3) near3 current) and "204"/\$.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 12:16 |
| S42 | 81 | S41 and (semiconductor adj wafer) | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/10 12:16 |